A close-up, angled view of a microchip die, showing a complex grid of circuitry with various colored regions (blue, green, yellow, red) and intricate patterns of metal and silicon.

Optimizing ECO efficiency and precision:

An alternative approach for
implementing digital-intensive RTL
module restructuring through metal
changes in IC design

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Agenda

1 Introduction

2 Standard ECO flow

3 Challenges

4 Proposed ECO flow

5 Conclusions

Engineering Change Order (ECO)



ECO

Engineering Change Order (ECO) is a process to implement device changes at a later stage of the development, without requiring a complete redesign of the chip.

This method provides a cost-effective and time-efficient solution to address:

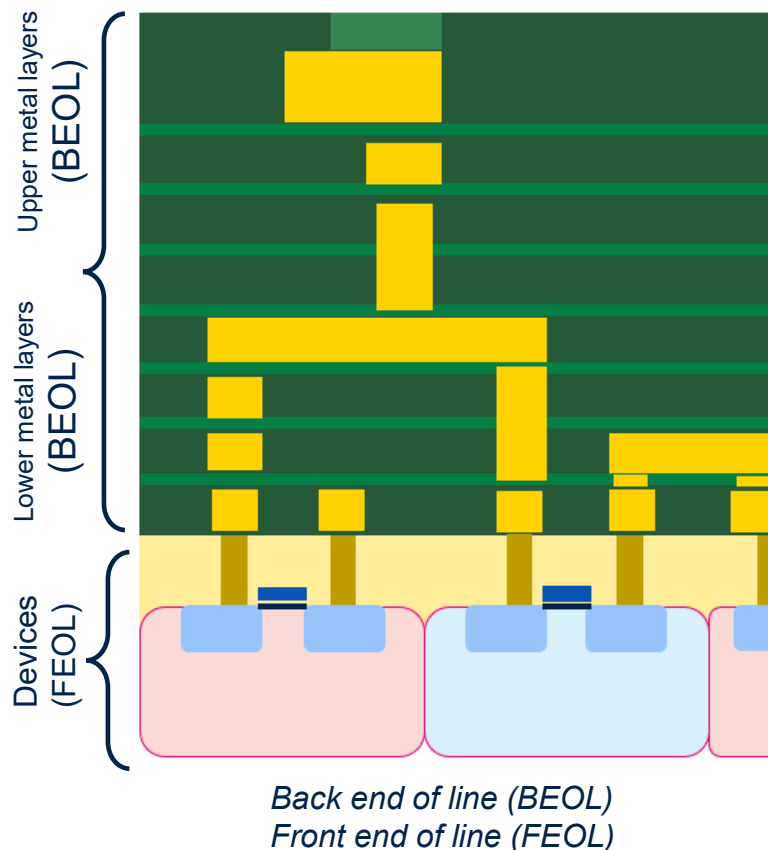
- Design errors
- Performance issue
- Design specification changes
- Bugs found during on-silicon testing

Types of ECOs

Full mask ECO FEOL + BEOL

Needed for major design changes or partial redesigns requiring new logic gates.

- ☹️ • More expensive
- ☹️ • Higher time to market
- 😊 • Suitable for complex changes
- 😊 • New cells are added/deleted, no need for spare cells

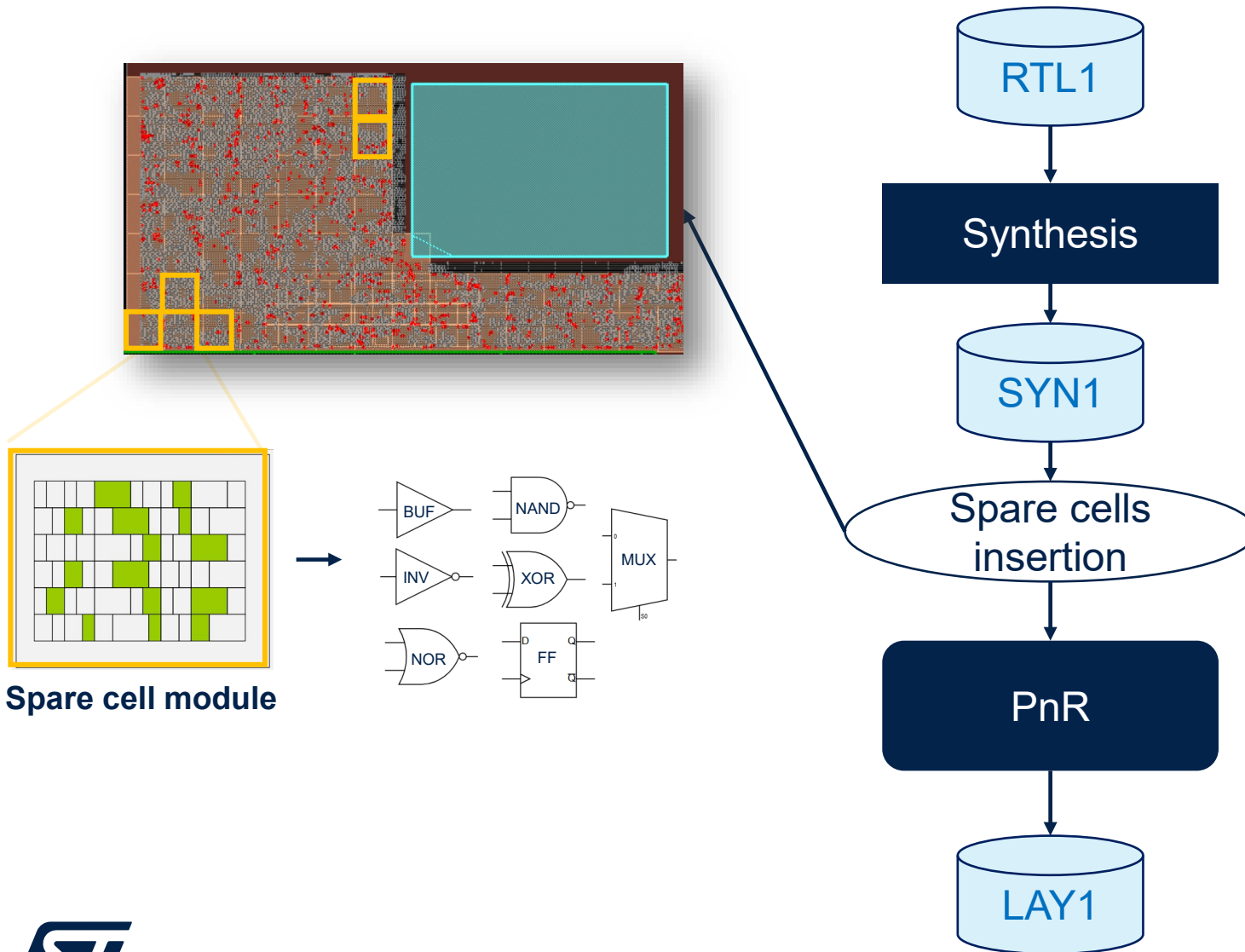


Metal mask ECO BEOL only

Ideal for minor fixes, reusing most existing design components and gates.

- 😊 • Cost-effective
- 😊 • Time saving
- ☹️ • Dependent on the complexity of design changes
- ☹️ • Limited by the availability of spare cells

ECO flow – pre tape-out

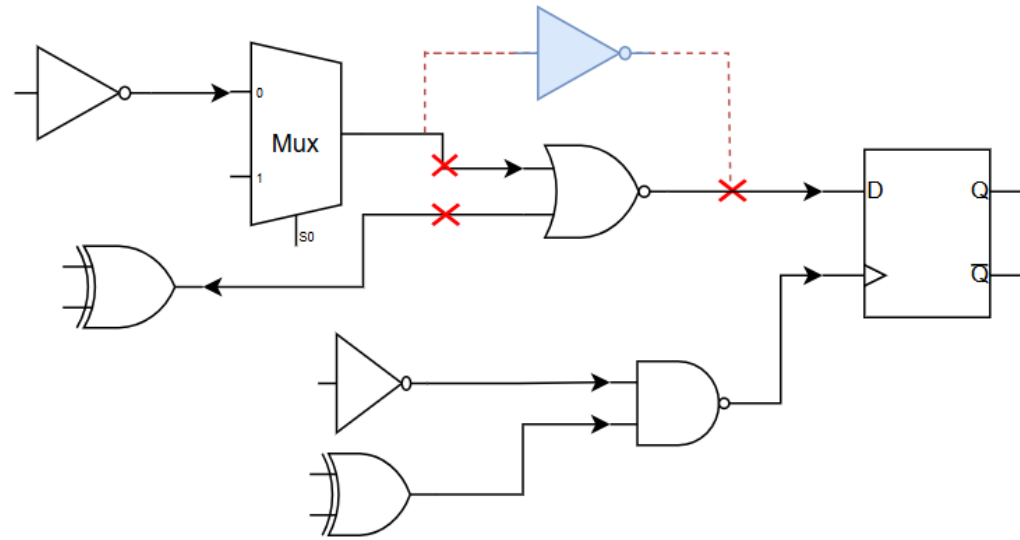


Spare cells are added during initial device implementation to support any future design changes after the tape-out.

- Topology is chosen between the most common cells of the design (NAND, NOR etc)
- Total number of spare is around 3-5% of total logic area
- Spare modules are evenly distributed inside the layout
- Inputs tied either VDD or VSS
- Outputs left floating

ECO flow – post tape-out (1/2)

For **small changes** → manual fix is applied to post-layout netlist

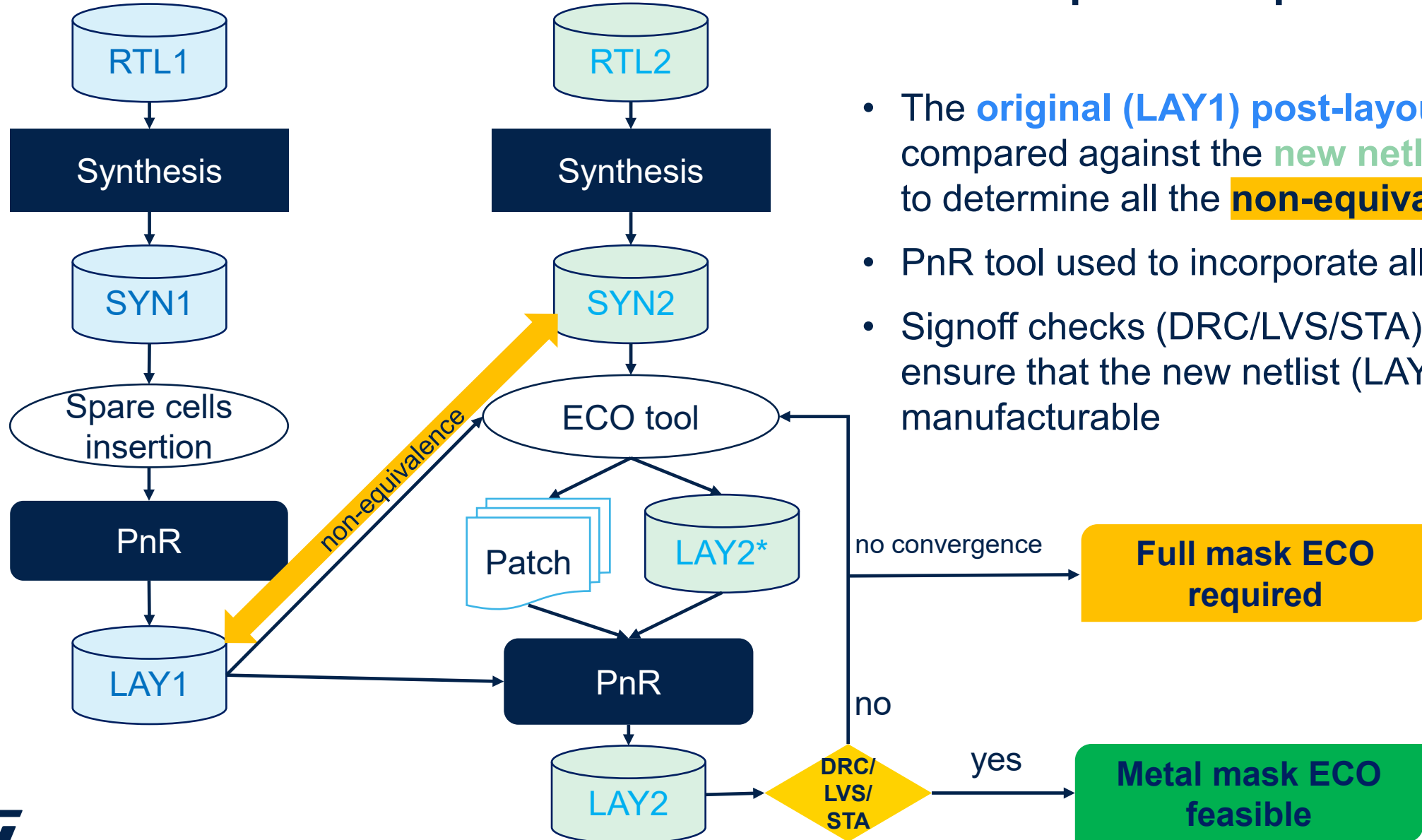


For **bigger changes** → specialized EDA tool is adopted (next slide)



Question: is metal ECO fix feasible?

ECO flow – post tape-out (2/2)



- The **original (LAY1) post-layout netlist** is compared against the **new netlist (SYN2)** to determine all the **non-equivalences**
- PnR tool used to incorporate all changes
- Signoff checks (DRC/LVS/STA) are run to ensure that the new netlist (LAY2) is manufacturable

Test case description (1/2)

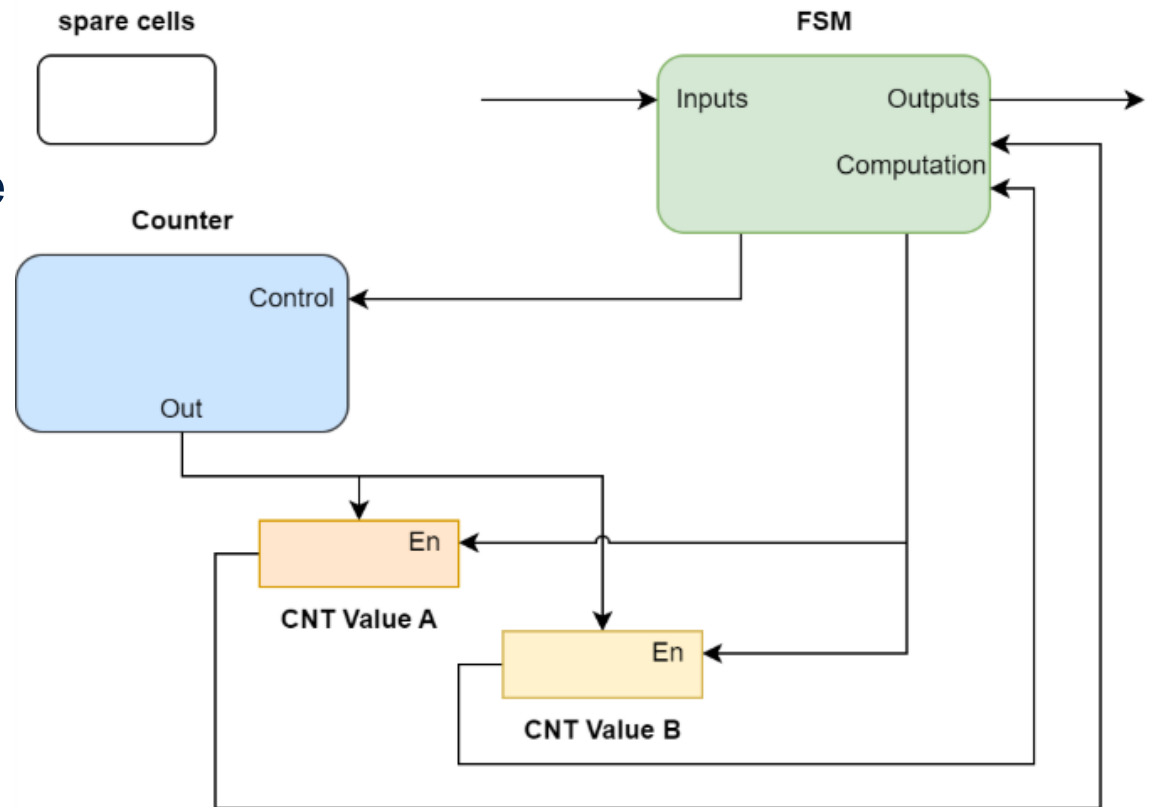
Original module architecture:

- Achieved area and performance trade-off using a single counter built from enlarged half-adder cells
- Control and sequencing managed by a Finite State Machine (FSM)



On-silicon testing revealed:

- Input signal dynamics were faster than anticipated
- FSM-based control introduced unacceptable computational latency



ORIGINAL ARCHITECTURE

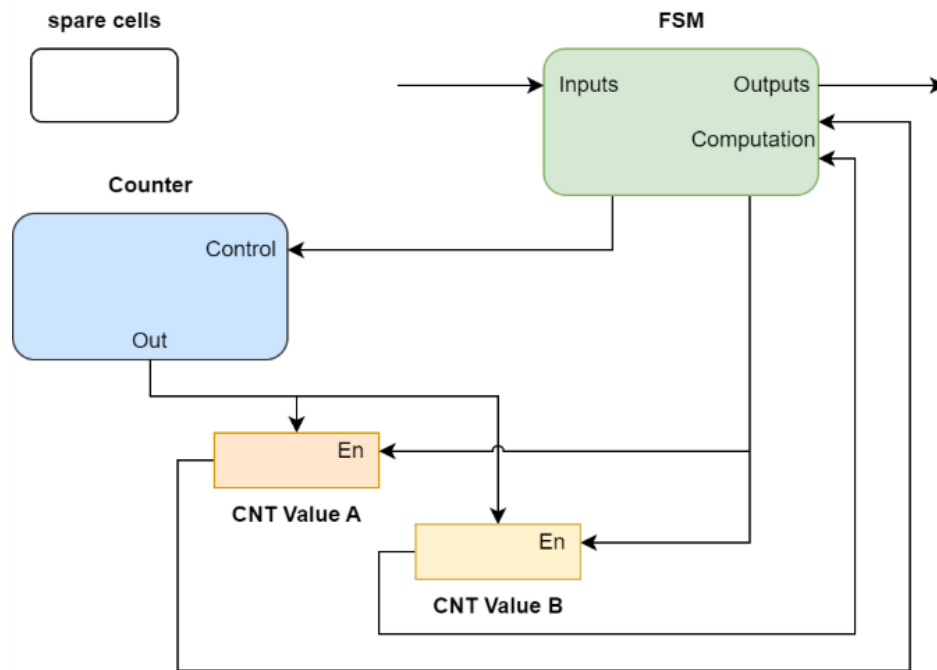
Test case description (2/2)

Identified limitation

FSM delays incompatible with rapid input transitions

Solution implemented

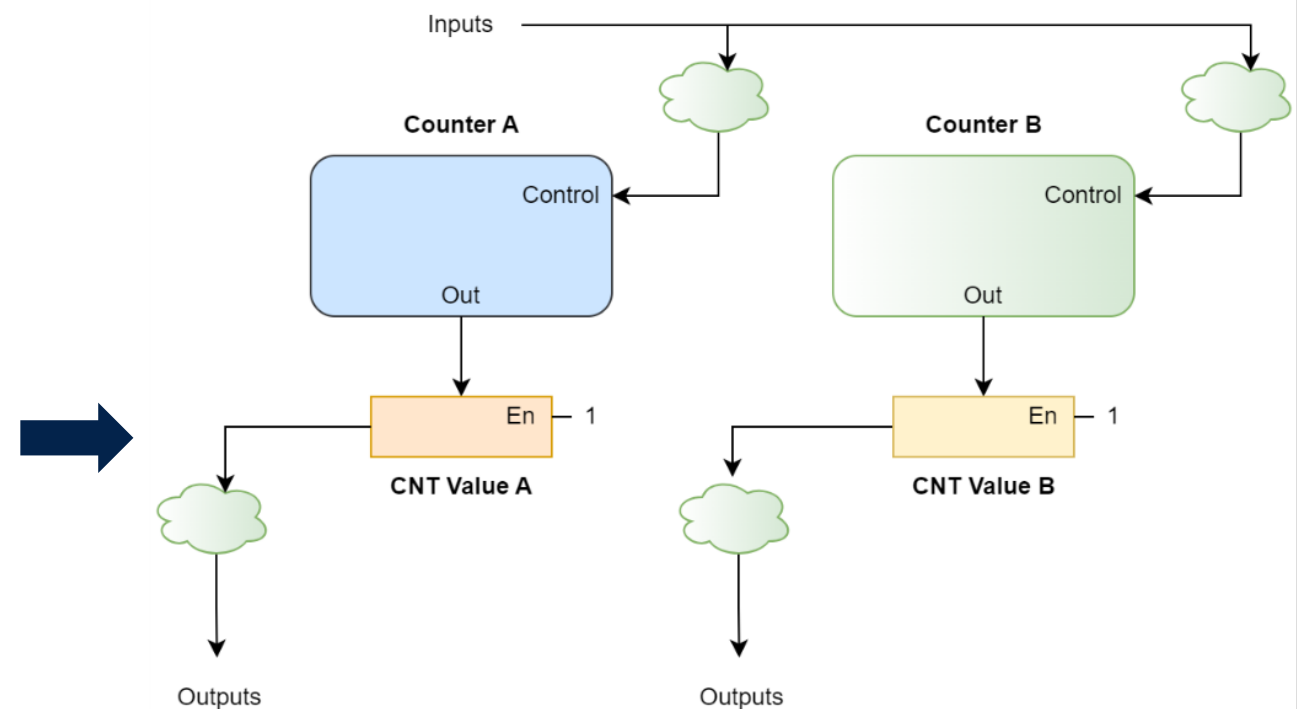
- Eliminated FSM
- Introduced a second counter



ORIGINAL ARCHITECTURE

Outcome

- Overcame hardware bottlenecks
- Met stringent timing requirements imposed by accelerated input signals



SOLUTION IMPLEMENTED

Standard ECO flow – Results

	Standard flow
Spare cells	149 logic instances 21 FF
Unused cone logic	Few existing cells (~10%) have been reused
CTS	Not balanced
DFT	Manual addition of new flops to existing scan chain
DRC	Long nets cause huge number of max cap/trans violations (>100)
DRV	Metal shorts and metal spacing violations (~250)

Key limitations

- ⚠ Extensive RTL-level modifications
- ⚠ Insufficient spare cells
- ⚠ Metal shorts & Timing violations

Conclusion:

- 🚫 Metal-only ECO not feasible with current implementation
- ⚠ Full mask set ECO required to handle the scope of changes

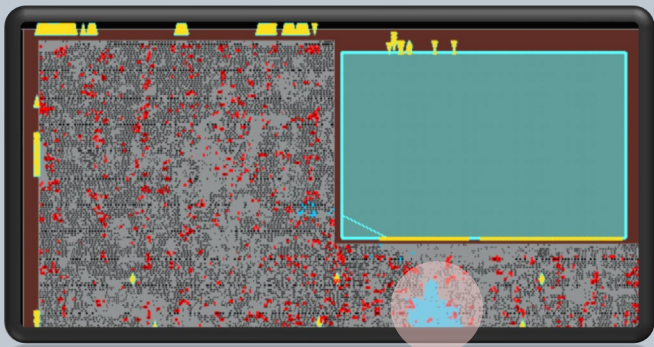
Standard ECO flow – challenges (1/2)

1

Spare cells

- Not enough **spare cells** in the area of the **RTL module**
- Spare cells are too far apart

→ Long nets/interconnections

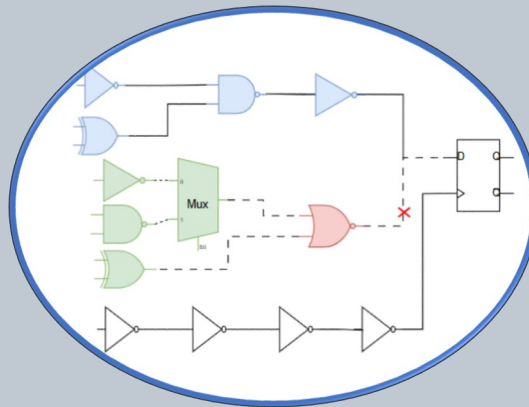


2

Unused logic cone

- Logic beyond the old connection point **(red)** is not reutilized
- Old **(Green)** logic is not remapped to the new **(blue)**

→ Power Consumption

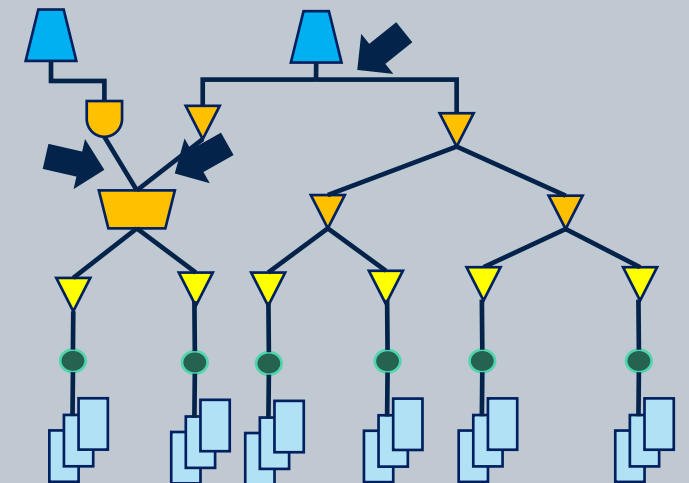


3

CTS

- New flops added to trunk nets (↙)
- No clock tree-balancing

→ setup and hold violations

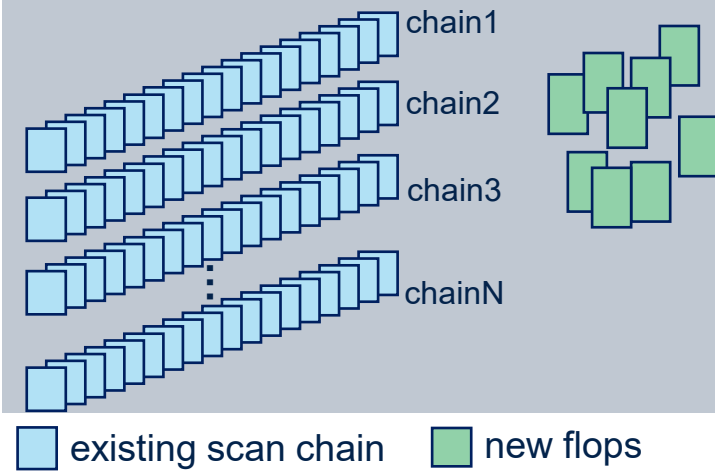


Standard ECO flow – challenges (2/2)

4

DFT

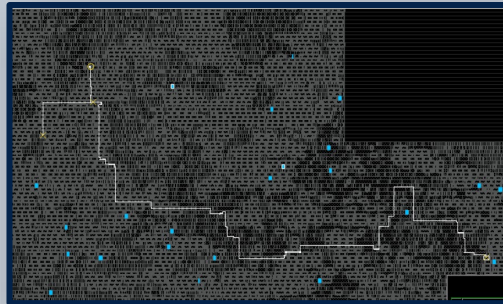
- New FFs are not connected to the existing scan chain
- Hand connection is necessary
- Impact on **DFT coverage**



5

DRV

- Distant spare cells → very long nets
- Max capacitance and max transition violations
- High number of buffers required



6

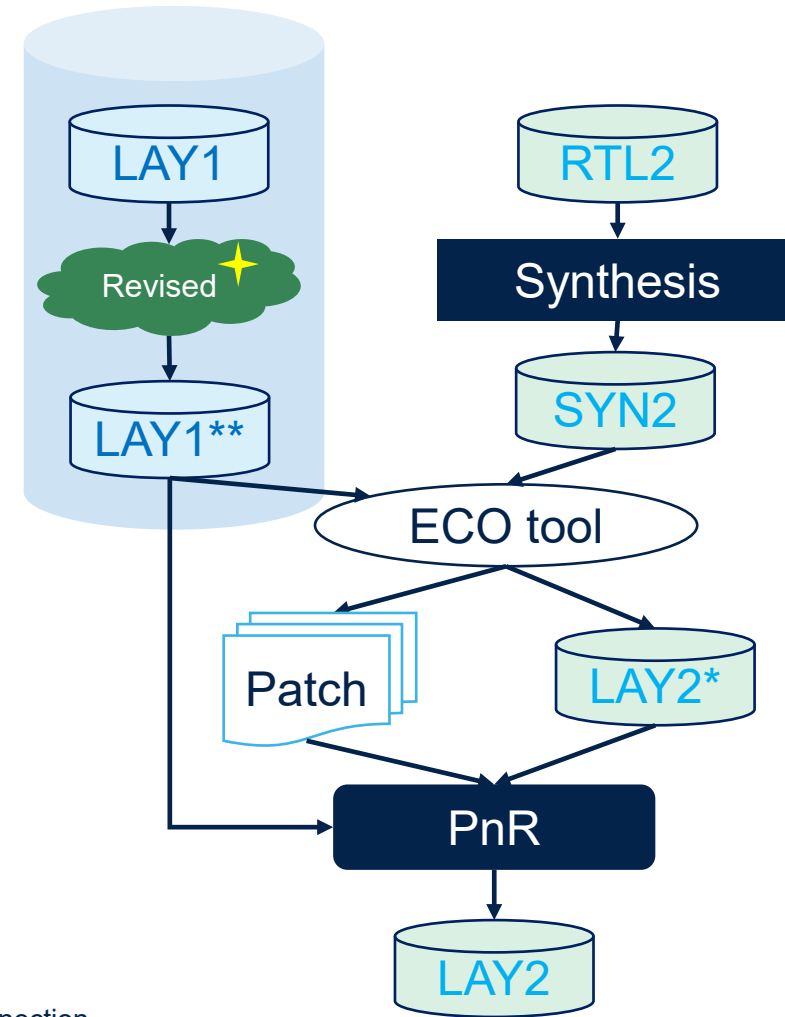
DRC

- Routing congestions
- Metal shorts
- NDR (non-default-rule)



Proposed ECO flow (1/3)

A **revised version** of the post-layout netlist is provided to the ECO tool. This netlist incorporates a series of **targeted modifications** aimed at **enhancing the tool's effectiveness** in resolving the issues encountered.



* netlist file (.v) with added instances and connection

** netlist file (.v) with targeted modifications

Proposed ECO flow (2/3)

Flip flop and DFT structure from original RTL module are **preserved** while all **combinational logic** gates are freed to become the new **“spare cells”**

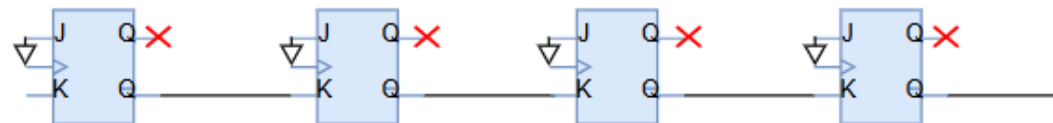
LAY1



new “spare” cells



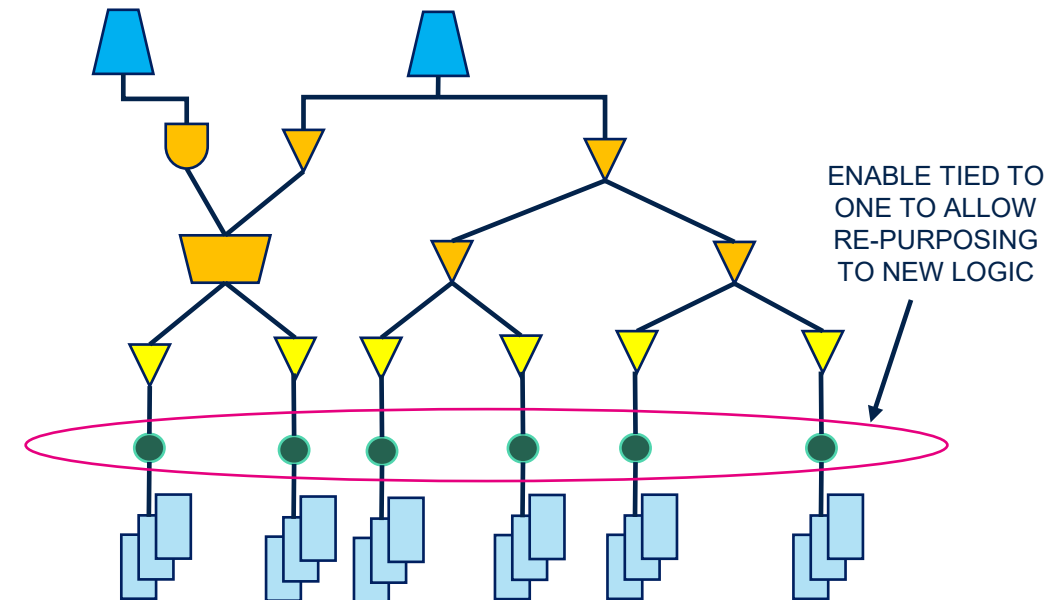
LAY1**



Clock tree structure is mostly preserved



Setup and hold timing ensured



- clock source
- clock trunk
- clock leaf
- flip flops
- clock gates

Proposed ECO flow (3/3)



RTL + Verilog

- Retained flip-flops, clock tree, and DFT structure
- Allowed reuse of logic gates between flip-flops
- Kept original RTL register names unchanged
- Maintained verification tool compatibility



ECO tool

- Reused majority of FSM logic to map the new counter logic
- Limited number of spare cells
- New flip flops of Counter B remapped to old unused flop logic from FSM



Place and route tool

- Reused all cells located in the area of the module being rewritten
- DFT coverage and scan chain length not impacted
- Better routability
- No metal shorts
- Setup/Hold timing MET

STANDARD ECO FLOW

21 spare FF
149 spare logic cells

Limited logic reuse (~10%)
unused logic disconnected

Clock-tree structure needs manual intervention
to fix setup and hold violations

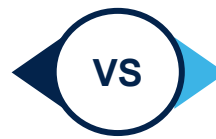
Manual addition of new Flip-Flops required
Unbalanced scan chains

Long nets
High max cap/trans violations (>100)

Routability issues, DRC (~250)
Metal shorts



Metal ECO is not feasible



Spare cells



Unused logic cone



CTS



DFT



DRV



DRC

PROPOSED ECO FLOW

0 spare FF
22 spare cells instances

New logic remapped from
previous FSM simplification (446 cells re-used/557)

Preserved synchronization between
existing flops (setup/hold MET)

Original scan chain and
DFT coverage preserved

Shorter nets
Low of max cap/trans violations (~30)

No routability issues
No metal shorts



Metal ECO is feasible

Summary and conclusion



- **RTL module redesign** was required to address hardware timing constraints identified during on-silicon validation.
- **Standard ECO flow** provides good automation and flexibility but exhibited limitations and challenges that initially made metal ECO implementation unfeasible.
- **Proposed ECO flow** maximizes reuse of existing standard cells, preserving flip-flops, clock tree, and scan chain connectivity of the original module design.
- Proposed ECO flow **overcomes the limitations of the standard approach** by improving efficiency and resolving routing and DRC issues.
- This approach **enabled metal ECO implementation** for extensive RTL restructuring, resulting in a significant **reduction in manufacturing costs**.

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